

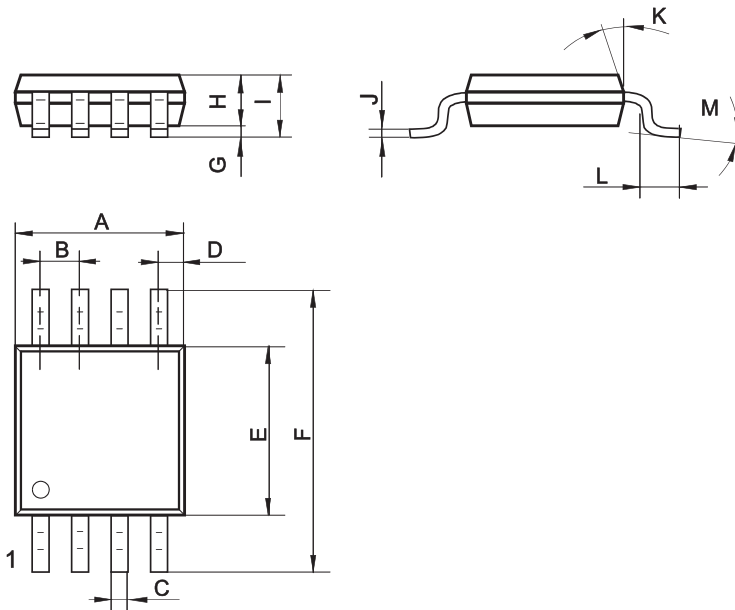
# PACKAGE DIMENSIONS

MSOP8/-TP, SSOP20/28, TSSOP16, TSSOP20/-TP, TSSOP24



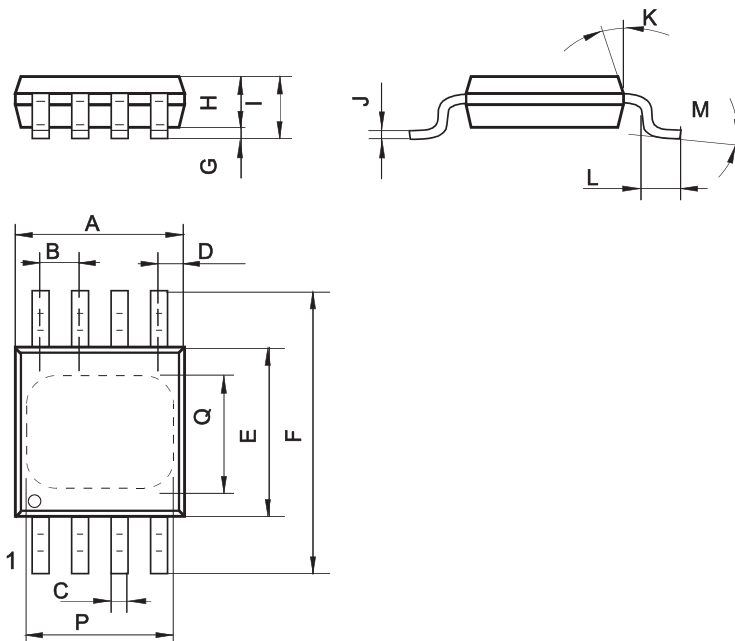
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## MSOP8



[mm]		
	Min.	Max.
A	2.9	3.1
B	0.65 BSC	
C	0.33	
D	0.475	0.575
E	2.9	3.1
F	4.75	5.05
G	0.05	0.15
H	0.78	0.94
I	-	1.1
J	0.1	-
K	9 DEG	15 DEG
L	0.4	0.7
M	0 DEG	6 DEG

## MSOP8-TP



[mm]		
	Min.	Max.
A	2.9	3.1
B	0.65 BSC	
C	0.33	-
D	0.475	0.575
E	2.9	3.1
F	4.75	5.05
G	0.05	0.15
H	0.78	0.94
I	-	1.1
J	0.1	-
K	9 DEG	15 DEG
L	0.4	0.7
M	0 DEG	6 DEG
P	1.70	
Q	1.73	

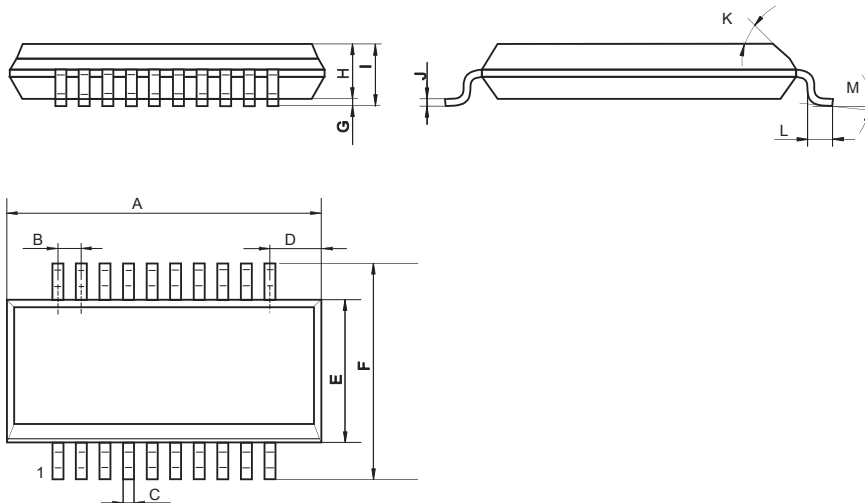
# PACKAGE DIMENSIONS

MSOP8/-TP, SSOP20/28, TSSOP16, TSSOP20/-TP, TSSOP24



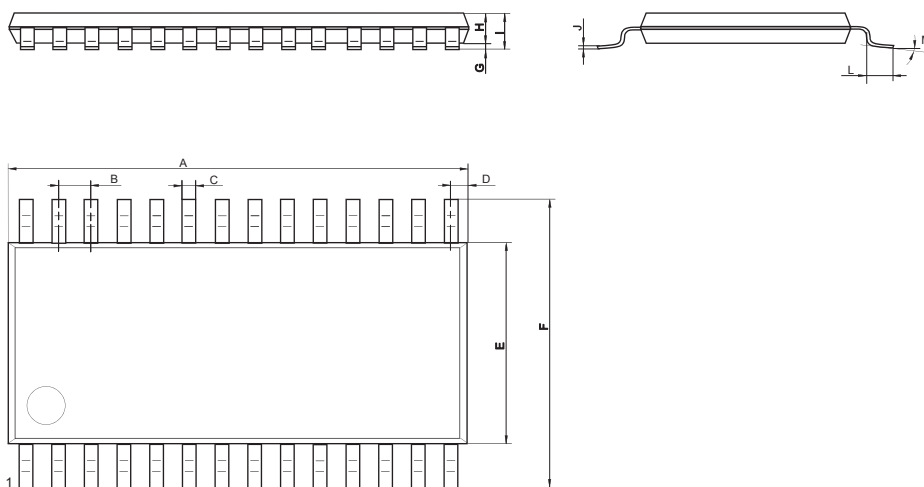
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## SSOP20 3.8 mm



[mm]		
	Min.	Max.
A	8.661	
B	0.635	
C	0.203	0.305
D	1.473	
E	3.912	
F	5.994	
G	0.102	0.249
H	1.397	1.549
I	1.549	1.727
J	0.178	0.254
K	45 DEG	
L	0.406	0.889
M	0 DEG	8 DEG

## SSOP28 5.3 mm



[mm]		
	Min.	Max.
A	10.07	10.33
B	0.65 BSC	
C	0.25	0.38
D	0.81	0.94
E	5.20	5.38
F	7.65	7.90
G	0.05	0.21
H	1.68	1.78
I	1.73	1.99
J	0.09	0.20
K	-	
L	0.63	0.95
M	0 DEG	8 DEG

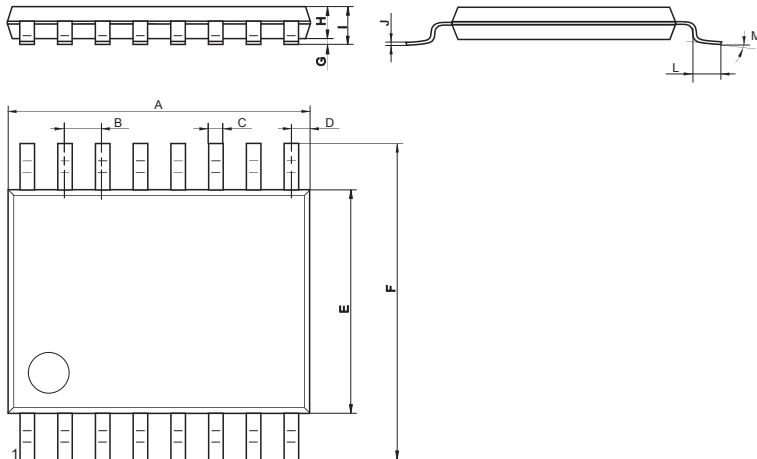
# PACKAGE DIMENSIONS

MSOP8/-TP, SSOP20/28, TSSOP16, TSSOP20/-TP, TSSOP24



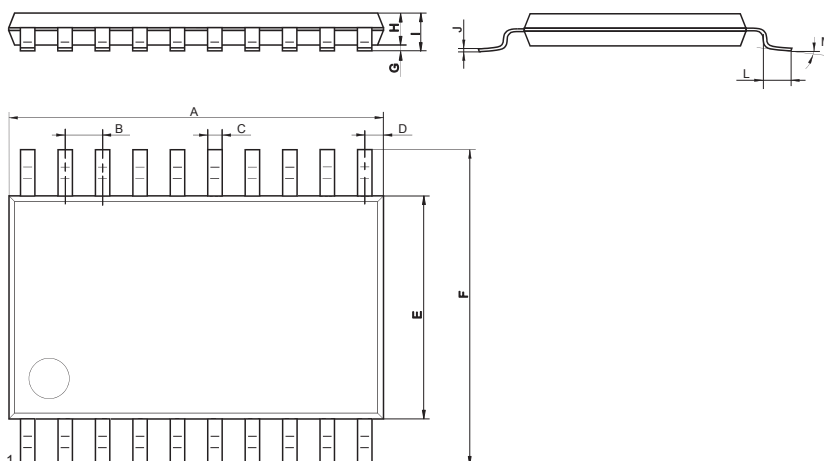
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## TSSOP16



[mm]		
	Min.	Max.
A	4.90	5.10
B	0.65 BSC	
C	0.19	0.30
D	0.175	0.275
E	4.30	4.50
F	6.40 BSC	
G	0.05	0.15
H	0.85	0.95
I	-	1.10
J	0.09	0.20
K	-	
L	0.50	0.70
M	0 DEG	8 DEG

## TSSOP20 4.4 mm



[mm]		
	Min.	Max.
A	6.40	6.60
B	0.65 BSC	
C	0.19	0.30
D	0.20	
E	4.30	4.50
F	6.40 BSC	
G	0.05	0.15
H	0.85	0.95
I	-	1.10
J	0.09	0.20
K	-	
L	0.50	0.70
M	0 DEG	8 DEG

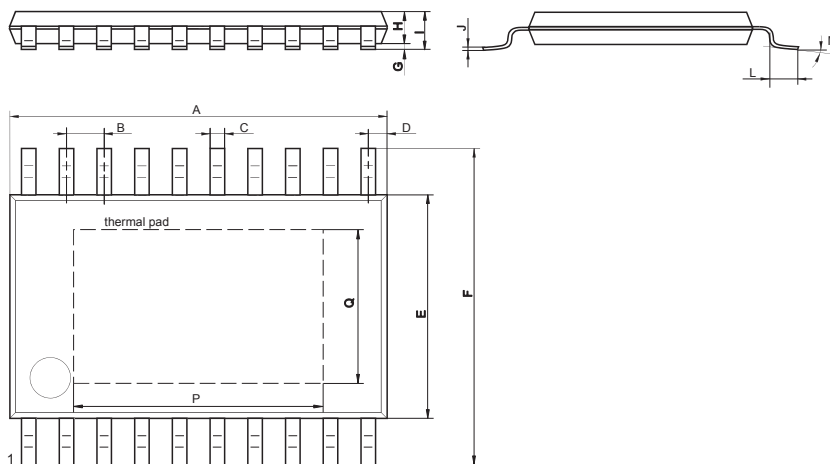
# PACKAGE DIMENSIONS

MSOP8/-TP, SSOP20/28, TSSOP16, TSSOP20/-TP, TSSOP24



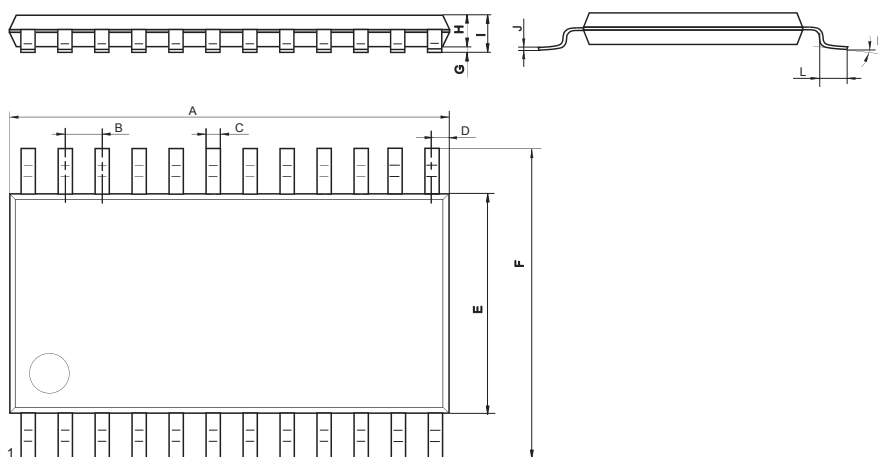
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## TSSOP20-TP 4.4 mm



[mm]		
	Min.	Max.
A	6.40	6.60
B	0.65 BSC	
C	0.19	0.30
D	0.20	
E	4.30	4.50
F	6.40 BSC	
G	0.05	0.15
H	0.85	0.95
I	-	1.10
J	0.09	0.20
K	-	
L	0.50	0.70
M	0 DEG	8 DEG
P	-	4.2
Q	-	3.0

## TSSOP24 4.4 mm



[mm]		
	Min.	Max.
A	7.70	7.90
B	0.65 BSC	
C	0.19	0.30
D	0.275	0.375
E	4.30	4.50
F	6.40 BSC	
G	0.05	0.15
H	0.85	0.95
I	-	1.10
J	0.09	0.20
K	-	
L	0.50	0.60
M	0 DEG	8 DEG

For additional information on component handling, preconditioning and soldering conditions, refer to the relevant iC-Haus customer information files, available separately.